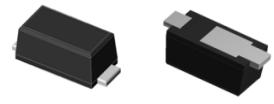


Features

- Super Low VF schottky barrier rectifiers
- Low profile, typical thickness 0.8mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Heatsink structure
- High temperature soldering guaranteed: 260°C/10 seconds



Package: iSGA
 (SOD-123HS)



RoHS
 COMPLIANT

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	GSPS32	GSPS33	GSPS34	GSPS345	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	45	V
Maximum RMS voltage	V_{RMS}	14	21	28	31.5	V
Maximum DC blocking voltage	V_{DC}	20	30	40	45	V
Maximum average forward rectified current	$I_{F(AV)}$			3.0		A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}			100		A
Rating for fusing($t < 8.3\text{ms}$)	I^2t			42		A^2sec
Operating junction temperature range	T_J		- 55 to + 150			°C
Storage temperature range	T_{STG}		- 55 to + 150			°C

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Value	Unit
Minimum Breakdown voltage	$T_A=25^\circ\text{C}, I_R=1\text{mA}$	V_{BR}	45	
Maximum instantaneous forward voltage	$I_F=3\text{A}, T_A=25^\circ\text{C}$	V_F	0.51	V
	$I_F=3\text{A}, T_A=125^\circ\text{C}$		0.45	
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^\circ\text{C}$	I_R	50	uA
	$T_A=125^\circ\text{C}$		10	
Typical junction capacitance	4.0 V, 1 MHz	C_J	229	pF
Typical thermal resistance	junction to ambient	$R_{\theta JA}^{(1)}$	60	°C/W
	junction to lead	$R_{\theta JL}^{(1)}$	6	
	junction to case	$R_{\theta JC}^{(2)}$	28	

Note:1),The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5×5mm copper pads,2 OZ,FR4 PCB

2),The thermal resistance from junction to case, mounted on P.C.B with recommended copper pads,2 OZ,FR4 PCB

Typical Electrical Characteristic Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

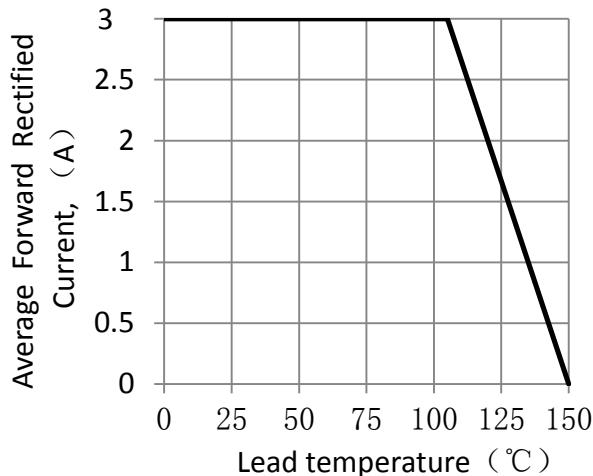


Figure 1. Forward Current Derating Curve

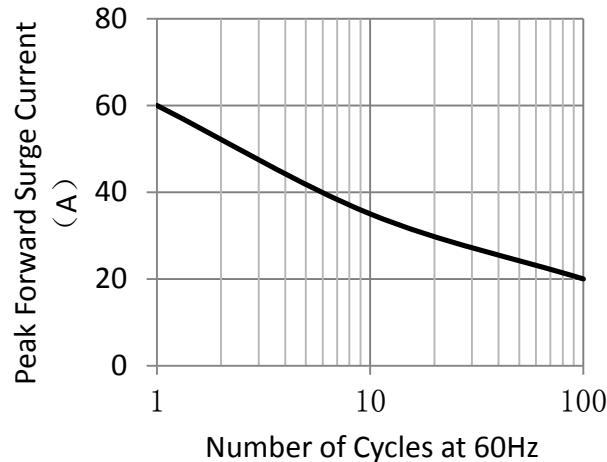


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

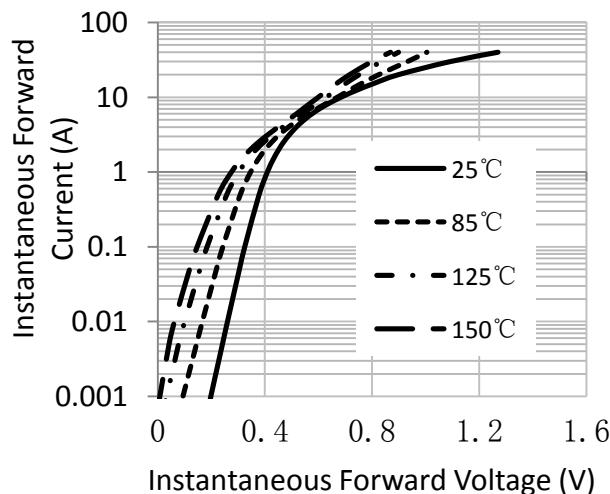


Figure 3. Typical Instantaneous Forward Characteristics

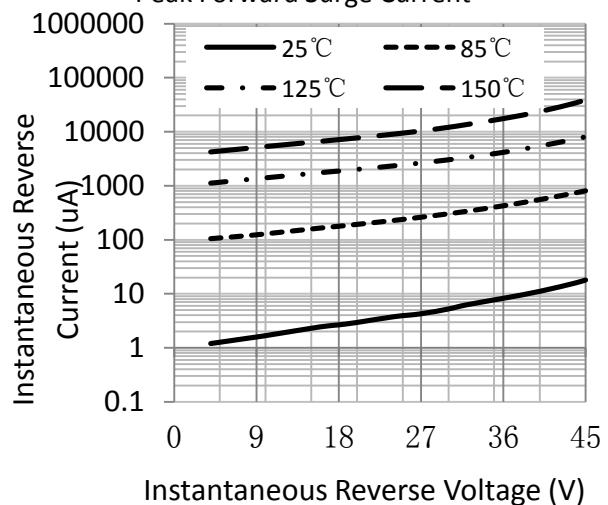


Figure 4. Typical Reverse Characteristics

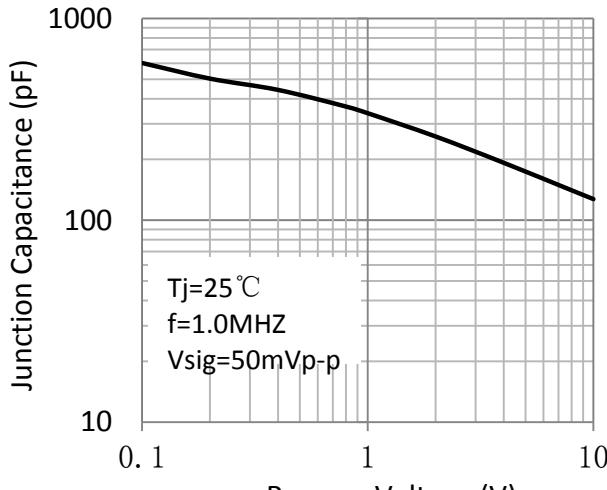
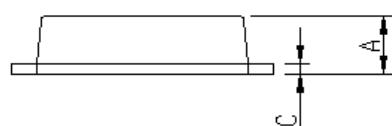
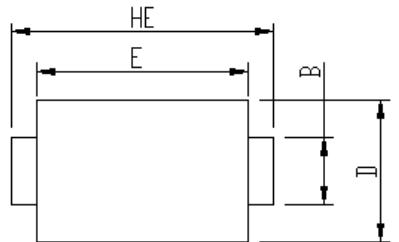


Figure 5. Typical Junction Capacitance

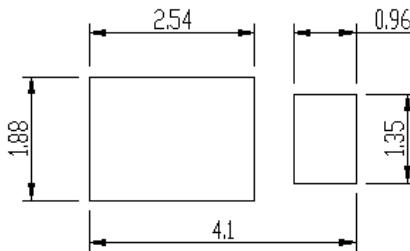
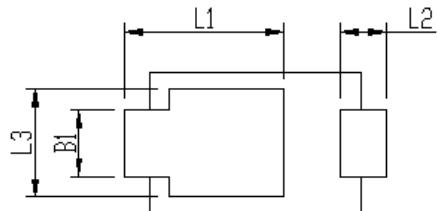
Package Outline Dimensions



Package: iSGA
 (SOD-123HS)

Package	iSGA	
Unit:mm	MIN	MAX
A	0.75	0.90
B	0.85	1.05
B1	0.85	1.05
C	0.1	0.25
D	1.9	2.1
E	2.9	3.1
L1	2.0	2.45
L2	0.4	0.85
L3	1.3	1.7
HE	3.5	3.9

Soldering footprint



Packing Information

Packing Quantities

Reel size	Quantity/reel	Quantity/inner Box	Quantity/Carton
7"	3K	30K	120K
13"	10K	20K	180K

Tape & Reel Specification

